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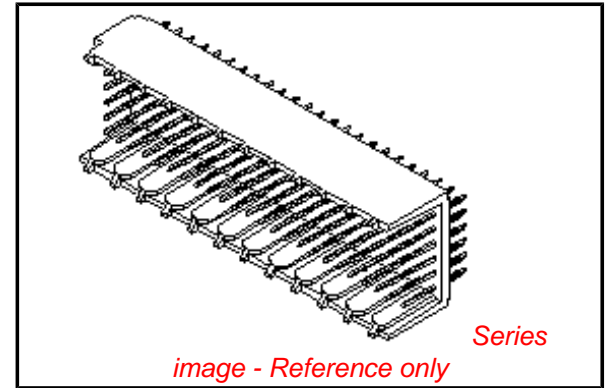
Part Number: [0736422209](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits, Lead Free

Documents:

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73670-9999 \(PDF\)](#)

General

Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.375
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
 Not Reviewed
**Halogen-Free
Status**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73642Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info**Reference - Drawing Numbers**

Product Specification	PS-73670-9999
Sales Drawing	SD-73642-003

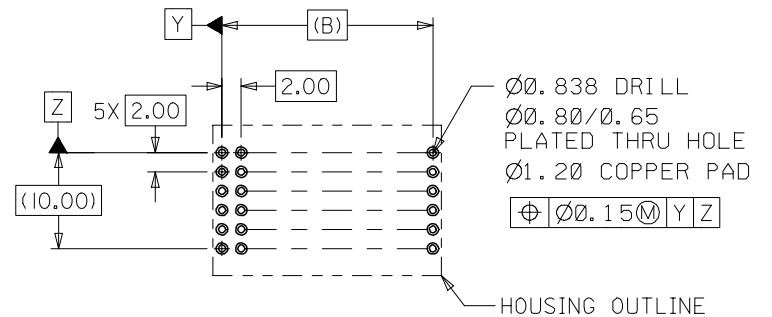
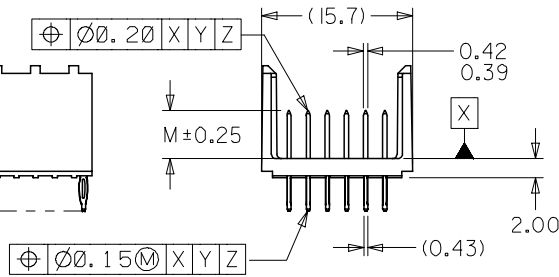
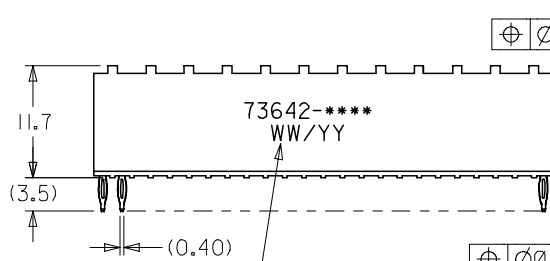
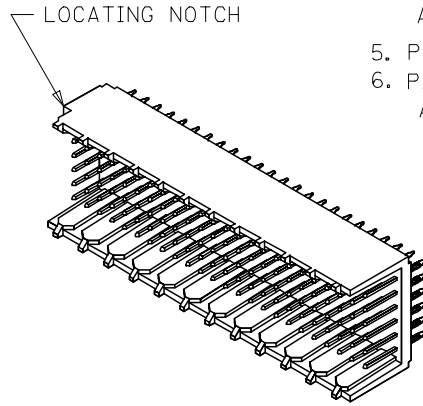
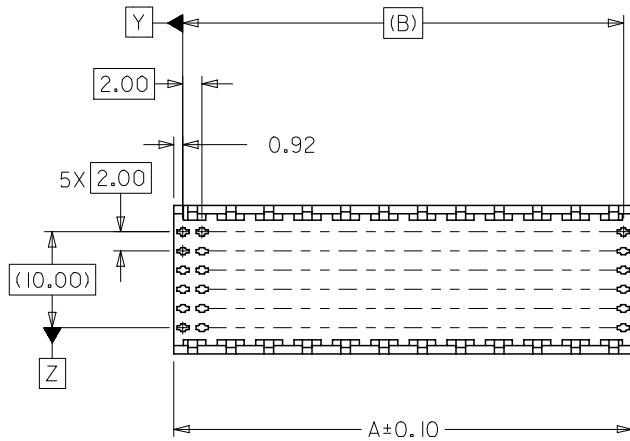
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This document was generated on 05/14/2010

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NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK,
TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA,
SELECTIVE TIN (Sn) IN TAIL AREA;
NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

INITIAL RELEASE EC NO: UCP2006-1564 DRW: JJONIAK 2006/01/31 CHKD: JBINGHAM 2006/01/31 APPR: CBI XLER 2006/02/02	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	2:1	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	JJONIAK	2005/11/01	SALES ASSEMBLY LEADFREE HDM BACKPLANE MODULE OPEN END OPTION	
2 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED MATERIAL NO. SEE PAGE 2 DOCUMENT NO. SD-73642-003 SHEET NO. 1 OF 2			
1 PLACE	± ---	± ---	JBINGHAM	2005/11/01				
ANGULAR ±1/2°		APPROVED BY		DATE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		JBINGHAM		2005/11/01				

10 9 8 7 6 5 4 3 2 1

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73642-2009	72	SELECTIVE GOLD/SELECTIVE TIN	23.84	22.00	5.00
73642-2109	72	SELECTIVE GOLD/SELECTIVE TIN	23.84	22.00	5.50
73642-2209	72	SELECTIVE GOLD/SELECTIVE TIN	23.84	22.00	6.00
73642-3009	144	SELECTIVE GOLD/SELECTIVE TIN	47.84	46.00	5.00
73642-3109	144	SELECTIVE GOLD/SELECTIVE TIN	47.84	46.00	5.50
73642-3209	144	SELECTIVE GOLD/SELECTIVE TIN	47.84	46.00	6.00

INITIAL RELEASE EC NO: UCP2006-1564 DRWN: JJONIAK 2006/01/31 CHKD: JBINGHAM 2006/01/31 APPR: CBI XLER 2006/02/02	DESCRIPTION REV A	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION															
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	APPROVED BY JBINGHAM	DATE 2005/11/01	ANGULAR ±1/2°		MOLEX INCORPORATED																			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-73642-003		SHEET NO. 2 OF 2																		

9 8 7 6 5 4 3 2 1